

02-27-2003

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copy thereof.

1. Name of conveying party(ies):

Leica Microsystems Inc. 2.24.03

Additional names of conveying parties attached? ☐ Yes ☒ No

2. Name and address of receiving party:

Name: Reichert, Inc.

Internal Address:

Street Address: 3374 Walden Avenue

City: Depew State: New York

Zip Code: 14043

Additional names and addresses attached? ☐ Yes ☒ No

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other

Execution Date: 01/28/2003

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s) 10/010,323

B. Patent No.(s)

Additional Numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: George L. Snyder, Jr.

Hodgson Russ LLP

Address: Intellectual Property Law Section

Street Address: One M&T Plaza, Suite 2000

City: Buffalo State: NY ZIP: 14203-2391

6. Total number of applications and patents involved: one

7. Total fee (37 CFR 3.41)..... \$40.00

☒ Enclosed☐ Authorized to be charged to deposit account

8. Deposit account number:

08-2442

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

George L. Snyder, Jr. Reg. No. 37,729
Name of Person Signing

Signature

February 19, 2003
Date

Total number of pages including cover sheet, attachments and document:

2

Mail documents to be recorded with required cover sheet information to:

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PATENT
REEL: 013780 FRAME: 0326

ASSIGNMENT OF INVENTION

In consideration of One Dollar (\$1.00), and other good and valuable consideration, the receipt of which is hereby acknowledged, **Leica Microsystems Inc.** (hereinafter Assignor) hereby sells, assigns, and transfers to **Reichert, Inc.** (hereinafter Assignee), a corporation of the State of Delaware having a place of business at 3374 Walden Avenue, Depew, New York 14043, its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, **Application No. 10/010323, filed 11/08/2001, which is entitled "METHOD FOR OPTIMIZING PISTON DIAMETER IN A NON-CONTACT TONOMETER, AND NON-CONTACT TONOMETER HAVING FLUID PUMP DESIGNED BY SAID METHOD,"** and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be issued in the United States and all foreign countries on said improvements;

Assignor agrees that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

Assignor covenants with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Leica Microsystems Inc.

Date 1-28-03

ME Wood
Mark Wood
Secretary